

patterning the organic insulating layer to form the protrusion and the spacer.

29. (Currently Added) The method of claim 28, wherein the organic insulating layer is photosensitive.

30. (Previously Presented) The method of claim 29, wherein the step of patterning the organic insulating layer comprises steps of:

preparing a mask layer having an opaque area, a semitransparent area and a transparent area on predetermined areas thereof;

exposing the photosensitive organic insulating film to a light beam through the mask layer; and

developing the photosensitive organic insulating layer to form the protrusion and the spacer.

31. (Previously Presented) The method of claim 30, wherein the spacer is formed at a portion of the photosensitive organic insulating layer corresponding to the opaque layer and the protrusion is formed at a portion of the photosensitive organic insulating layer corresponding to the semitransparent pattern.

32. (Previously Presented) The method of claim 30, wherein the spacer is formed at a portion of the photosensitive organic insulating layer corresponding to the transparent layer and the protrusion is formed at a photosensitive portion of the organic insulating layer corresponding to the semitransparent pattern.

33. (Currently Added) The method of claim 27, wherein the step of forming the protrusion and the spacer comprises steps of:

forming an insulating layer on the conductive layer;

forming a photoresist layer on the insulating layer; and

patterning the insulating layer and photoresist layer to form the protrusion and the spacer.

34. (Previously Presented) The method of claim 33, wherein the step of patterning the insulating layer and photoresist layer comprising steps of:

preparing a mask layer having an opaque area, a semitransparent area and a transparent area on predetermined areas thereof;

exposing the photoresist layer to a light beam through the mask layer;

developing the photoresist layer to expose portions of the insulating layer; and

etching the exposed portions of the insulating layer.

35. (Previously Presented) The method of claim 34, wherein the insulating layer contains silicon.

36. (Previously Presented) The method of claim 27, further comprising a step of forming a black matrix layer on the substrate.

37. (Previously Presented) The method of claim 36, wherein the black matrix layer is formed between the substrate and the color filter layer.

38. (Currently Added) The method of claim 37, wherein the protrusion and the spacer are formed on the black matrix layer.

39. (Previously Presented) A method for manufacturing a liquid crystal display (LCD), comprising steps of:

forming a black matrix layer on a first substrate, the black matrix layer comprising a first black matrix pattern surrounding a pixel region and a second black matrix pattern formed within the pixel region;

forming a color filter layer on the black matrix layer;

forming a conductive layer on the color filter layer; and

forming a protrusion on a portion of the conductive layer corresponding to the second black matrix pattern, the protrusion having a height to maintain a predetermined gap between the first substrate and a second substrate facing the first substrate.

40. (Previously Presented) The method of claim 39, wherein the height of the protrusion ranges between 3.0  $\mu\text{m}$  and 4.5  $\mu\text{m}$ .

41. (Previously Presented) The method of claim 39, wherein the protrusion is pillar-shaped.

42. (Previously Presented) The method of claim 41, wherein a top surface and a bottom surface of the protrusion have a circular or rectangular shape or a rectangular shape with curved edges.

43. (Previously Presented) The method of claim 39, wherein the protrusion is formed of a photosensitive material, positive or negative photoresist or an insulating material containing silicon.

44. (Previously Presented) The method of claim 39, wherein the pixel region is divided into a plurality of sub-regions and the protrusion is formed within each sub-region.

45. (Previously Presented) The method of claim 44, wherein the protrusion is formed at the center of each sub-region.

46. (Previously Presented) The method of claim 39, wherein the protrusion is in contact with a pixel electrode of the second substrate to maintain the predetermined gap between the first substrate and the second substrate.